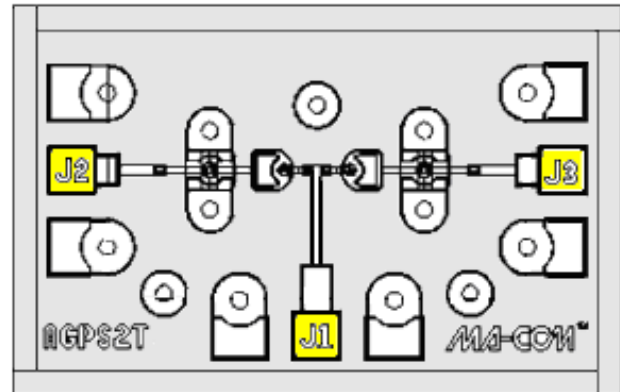


SPDT AlGaAs PIN Diode Switch

Rev. V7

Features

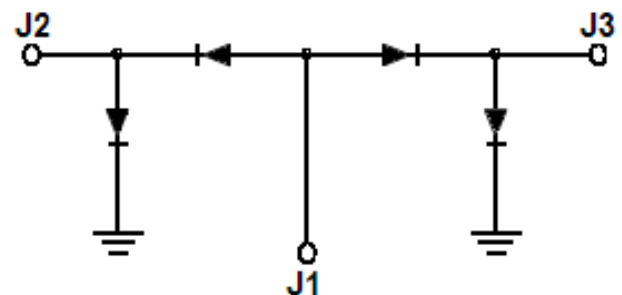
- Ultra Broad Bandwidth: 50 MHz to 50 GHz
- Functional Bandwidth: 50 MHz to 70 GHz
- Insertion Loss: 0.7 dB
- Isolation: 33 dB @ 50 GHz
- Low Current Consumption:
 - 10 mA for Low Loss State
 - +10 mA for Isolation State
- MACOMs Unique AlGaAs Hetero-Junction Anode Technology
- Silicon Nitride Passivation
- Polymer Scratch protection
- RoHS Compliant



Yellow areas indicate bond pads

Description

The MA4AGSW2 is an Aluminum-Gallium-Arsenide, single pole, double throw (SPDT), PIN diode switch. The switch features enhanced AlGaAs anodes which are formed using MACOM's hetero-junction technology. AlGaAs technology produces a switch with less loss than a device fabricated using conventional GaAs processes. As much as a 0.3 dB reduction in insertion loss can be realized at 50 GHz. This device is fabricated on an OMCVD epitaxial wafer using a process designed for high device uniformity and extremely low parasitics. The diodes within the chip exhibit low series resistance, low capacitance, and fast switching speed. They are fully passivated with silicon nitride and have an additional polymer layer for scratch protection. The protective coating prevents damage during handling and assembly to the diode junction and the chip anode air-bridges. Off chip bias circuitry is required.



Applications

The high electron mobility of AlGaAs and the low capacitance of the PIN diodes used makes this switch ideal for fast response, high frequency, multi-throw switch designs. AlGaAs PIN diode switches are an ideal choice for switching arrays in radar systems, radiometers, test equipment and other multi-assembly components.

Ordering Information

Part Number	Package
MA4AGSW2	waffle pack
MASW-000552-13210G	Gel Pack

Electrical Specifications:

$T_A = +25^\circ\text{C}$, ± 15 mA Bias Current, 0 V (on-wafer measurements)

Parameter	Test Conditions	Units	Min.	Typ.	Max.
Insertion Loss	0.05 - 18 GHz 18 - 50 GHz	dB	—	0.5 0.7	0.6 0.9
Isolation	0.05 - 18 GHz 18 - 50 GHz	dB	45 28	47 33	—
Input Return Loss	0.05 - 18 GHz 18 - 50 GHz	dB	—	22 21	—
Output Return Loss	0.05 - 18 GHz 18 - 50 GHz	dB	—	25 22	—
Switching Speed ¹ (10 - 90% RF Voltage)	± 5 V TTL Compatible PIN Diode Driver, 10 GHz	ns	—	20	—

1. Typical switching speed is measured from 10% to 90% of the detected RF voltage driven by a ± 5 V TTL compatible driver. Driver output parallel RC network uses a capacitor between 390 - 560 pF and a resistor between 150 - 220 Ω to achieve 15 ns rise and fall times.

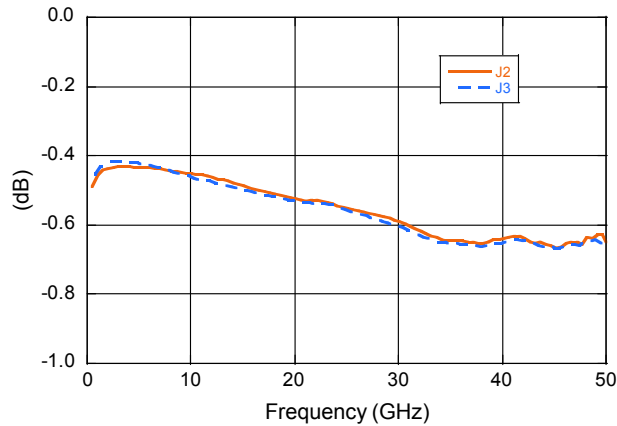
Absolute Maximum Ratings² @ $T_A = +25^\circ\text{C}$

Parameter	Absolute Maximum
Incident C.W. RF Power	23 dBm
Breakdown Voltage	25 V
Bias Current	± 25 mA
Junction Temperature	$+175^\circ\text{C}$
Operating Temperature	-55°C to $+125^\circ\text{C}$
Storage Temperature	-55°C to $+150^\circ\text{C}$
Assembly Temperature	$+300^\circ\text{C} < 10$ sec.

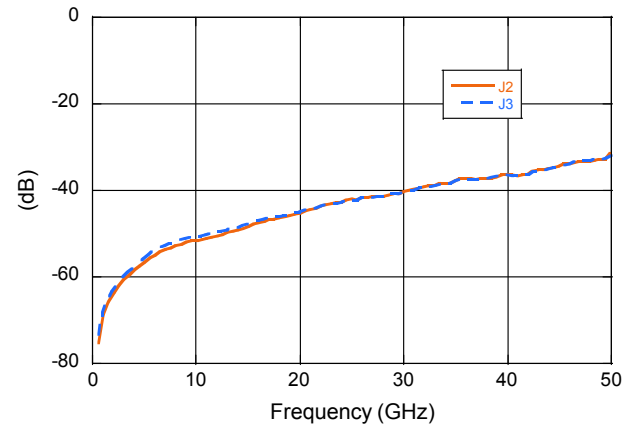
2. Maximum combined operating conditions for RF Power, DC bias, and temperature: 23 dBm C.W. @ 10 mA (per diode) @ $+85^\circ\text{C}$.

Typical RF Performance Curves @ +25°C (probed on wafer)

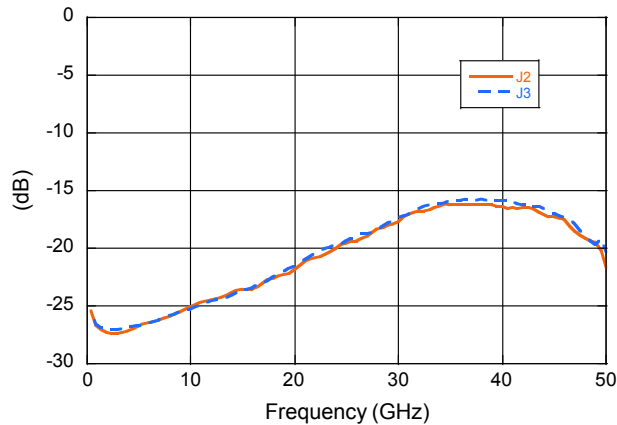
Insertion Loss @ -10 mA



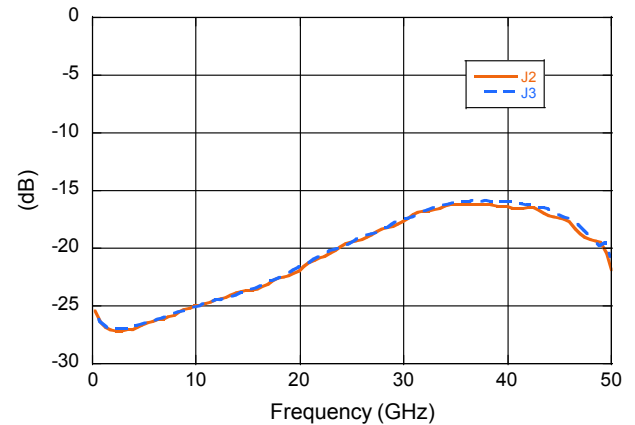
Isolation @ +10 mA



Input Return Loss @ -10 mA



Output Return Loss @ -10 mA

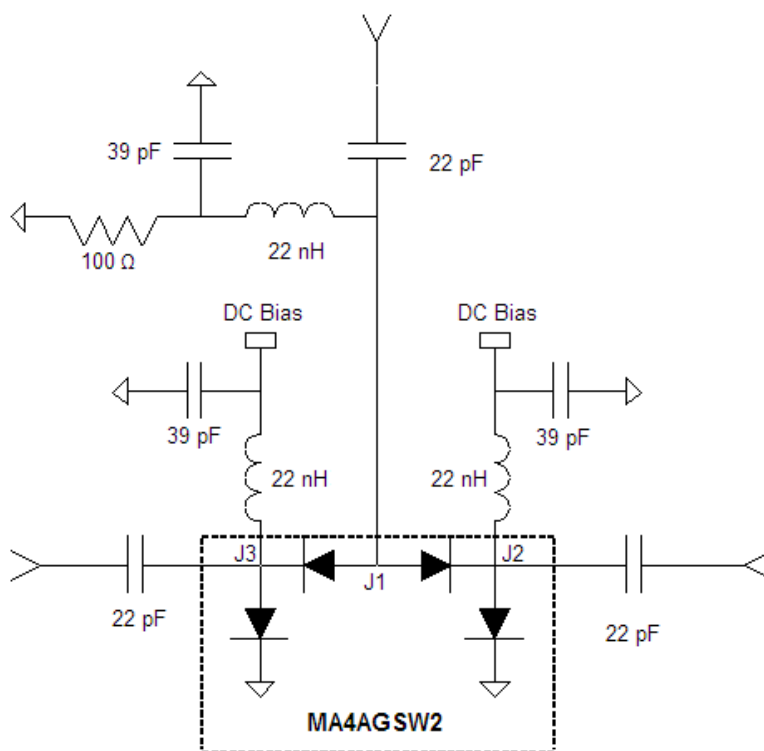


Operation of the MA4AGSW2 Switch

The simultaneous application of a negative DC current to the low loss port and positive DC current to the remaining isolated switching port is required for the operation of the MA4AGSW2, AlGaAs, PIN switch. The backside area of the die is the RF and DC return ground plane. The DC return is connected to the common port J1. The forward bias voltage at J2 & J3 will not exceed ± 1.6 V and is typically ± 1.4 V with supply current of ± 30 mA. In the low loss state, the series diode must be forward biased and the shunt diode reverse biased. While for the Isolated port, the shunt diode is forward biased and the series diode is reverse biased. The bias network design shown below should yield >30 dB RF to DC Isolation.

The lowest insertion loss, P1dB, IP3, and switching speed is achieved by using a voltage pull-up resistor in the DC return path, (J1). A minimum value of $|-2$ V | is recommended at this return node, which is achievable with a standard, ± 5 V TTL Controlled PIN Diode Driver.

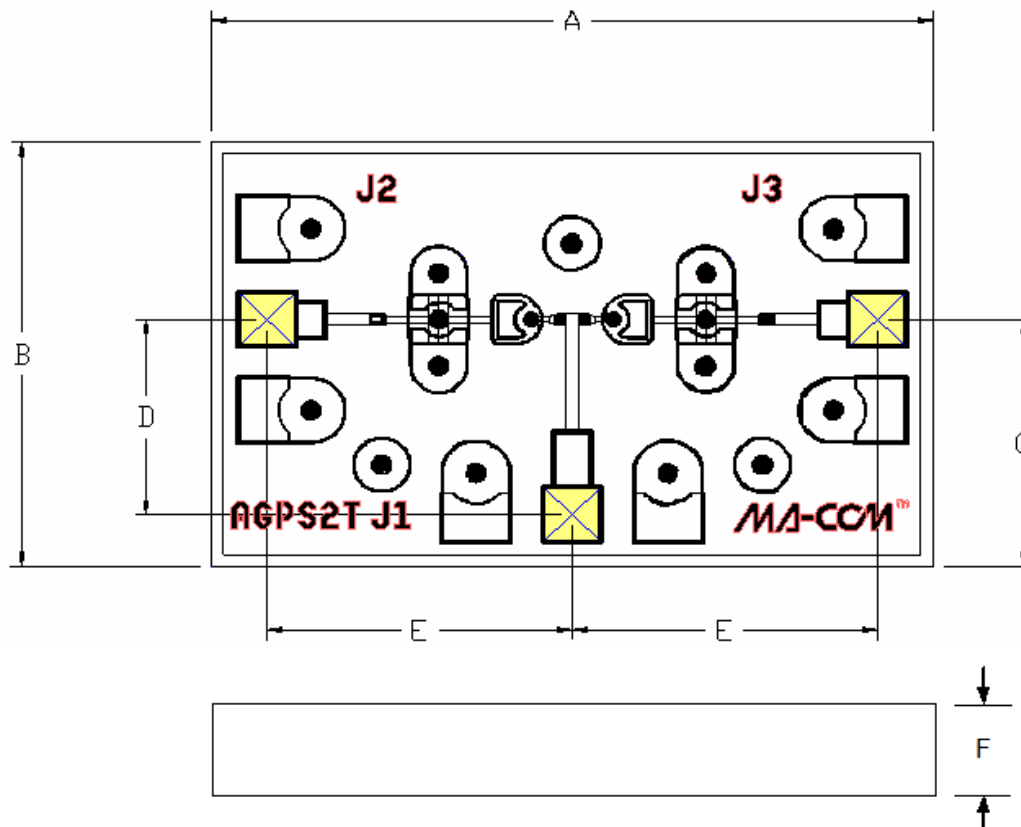
MA4AGSW2 Schematic with a Typical External 2-18 GHz Bias Network



Typical Driver Connections

Control Level (DC Current)		RF Output State	
J2	J3	J2 - J1	J3 - J1
-10 mA	+10 mA	Low Loss	Isolation
+10 mA	-10 mA	Isolation	Low Loss

Chip Dimensions and Bonding Pad Locations (In Yellow)



Dimensions	mils			mm		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	48	49	50	1.219	1.245	1.270
B	29.7	30.7	31.7	0.754	0.780	0.805
C	17.3	17.8	18.3	0.439	0.452	0.465
D	13.7	13.9	14.1	0.348	0.358	0.358
E	20.3	20.5	20.7	0.516	0.521	0.526
F	3.5	4.0	4.5	0.094	0.099	0.109
Pads X-Y	3.5	4.0	4.5	0.089	0.102	0.114

Assembly Instructions

Cleanliness

The chip should be handled in a clean environment.

Static Sensitivity

This device is considered ESD Class 1A, HBM. Proper ESD techniques should be used during handling.

General Handling

The protective polymer coating on the active areas of the die provides scratch and impact protection, particularly for the metal air bridge, which contacts the diode's anode. Die should primarily be handled with vacuum pickup tools, or alternatively with plastic tweezers.

Assembly Techniques

The MA4AGSW2, AlGaAs switch is designed to be mounted with electrically conductive silver epoxy or with a low temperature solder perform, which does not have a rich tin content.

Solder DIE Attach

Only solders which do not scavenge gold, such as 80Au/20Sn or Indalloy #2 is recommended. Do not expose die to temperatures >300°C for more than 10 seconds.

Conductive Epoxy DIE Attach

Use a controlled thickness of approximately 2 mils for best electrical conductivity and lowest thermal resistance. Cure epoxy per manufacturer's schedule. Typically 150°C for 1 hour.

Ribbon/Wire Bonding

Thermo-compression wedge or ball bonding may be used to attach ribbons or wire to the gold bonding pads. A 1/4 x 3 mil gold ribbon is recommended on all RF ports and should be kept as short as possible for the lowest inductance and best microwave performance. For more detailed handling and assembly instructions, see [Application Note M541](#), "Bonding and Handling Procedures for Chip Diode Devices" at www.macom.com.

MACOM Technology Solutions Inc. All rights reserved.

Information in this document is provided in connection with MACOM Technology Solutions Inc ("MACOM") products. These materials are provided by MACOM as a service to its customers and may be used for informational purposes only. Except as provided in MACOM's Terms and Conditions of Sale for such products or in any separate agreement related to this document, MACOM assumes no liability whatsoever. MACOM assumes no responsibility for errors or omissions in these materials. MACOM may make changes to specifications and product descriptions at any time, without notice. MACOM makes no commitment to update the information and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to its specifications and product descriptions. No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document.

THESE MATERIALS ARE PROVIDED "AS IS" WITHOUT WARRANTY OF ANY KIND, EITHER EXPRESS OR IMPLIED, RELATING TO SALE AND/OR USE OF MACOM PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, CONSEQUENTIAL OR INCIDENTAL DAMAGES, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT. MACOM FURTHER DOES NOT WARRANT THE ACCURACY OR COMPLETENESS OF THE INFORMATION, TEXT, GRAPHICS OR OTHER ITEMS CONTAINED WITHIN THESE MATERIALS. MACOM SHALL NOT BE LIABLE FOR ANY SPECIAL, INDIRECT, INCIDENTAL, OR CONSEQUENTIAL DAMAGES, INCLUDING WITHOUT LIMITATION, LOST REVENUES OR LOST PROFITS, WHICH MAY RESULT FROM THE USE OF THESE MATERIALS.

MACOM products are not intended for use in medical, lifesaving or life sustaining applications. MACOM customers using or selling MACOM products for use in such applications do so at their own risk and agree to fully indemnify MACOM for any damages resulting from such improper use or sale.



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.